



LIGHT ELECTRONICS CO., LTD.



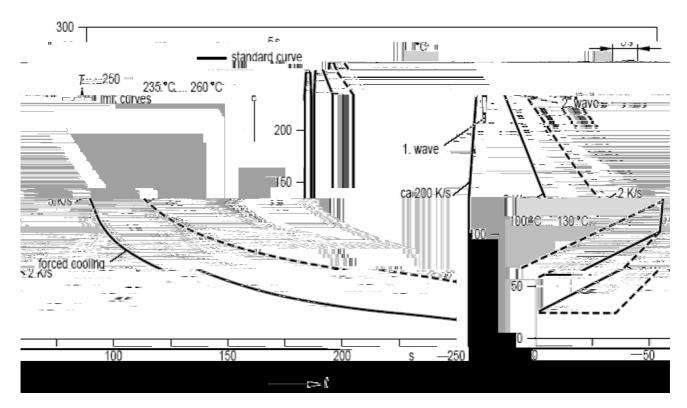
Electrical Optical Characteristics at Ta=25

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition	
Radiant Intensity	Ie	2.2	3.0		mW/sr	I _F =20mA (Note 1,3)	
Viewing Angle	2 _{1/2} 130 deg (Note 2		(Note 2)				
Peak Wavelength	p		940		nm	I _F =20mA	
Spectral Line Half- Width			50		nm	I _F =20mA	
Forward Voltage	V_{F}		1.25	1.60	V	I _F =50mA	
Reverse Current	I_R			100	μΑ	V _R =5V	

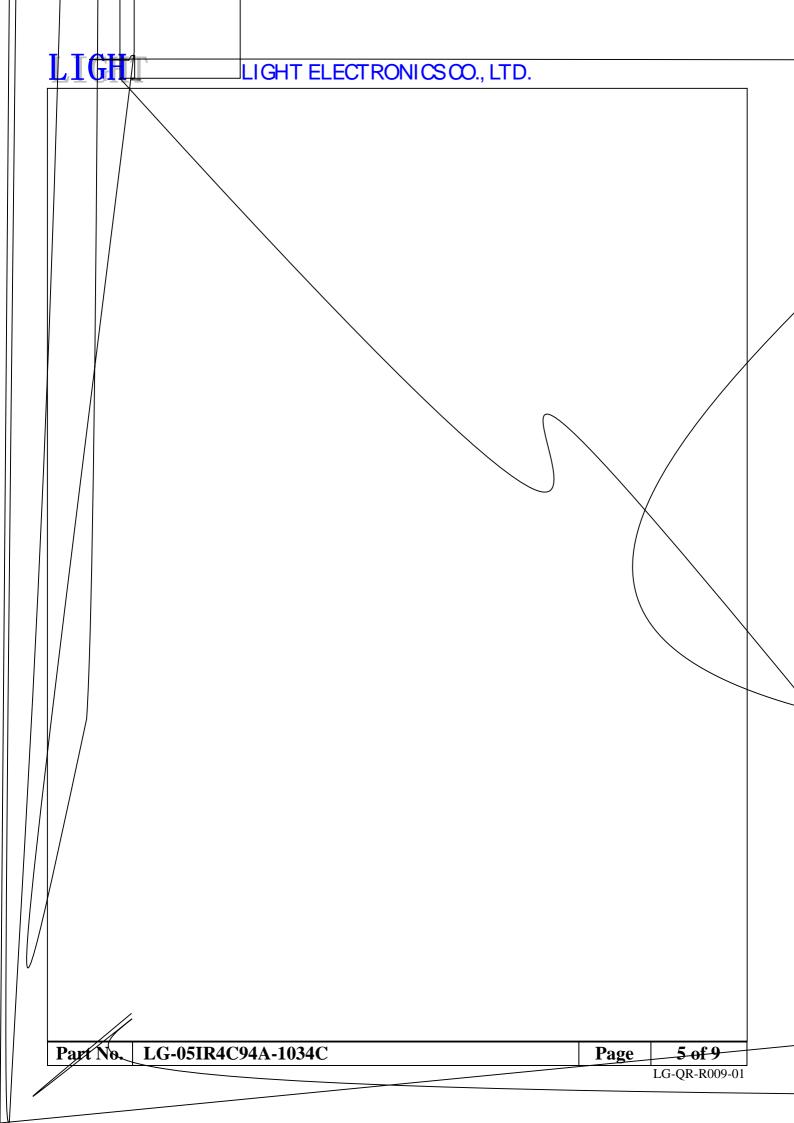
Note:

- 1. Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.
- 2. _{1/2} is the off-axis angle at which the Radiant Intensity is half the axial Radiant Intensity.
- 3. The Ie guarantee should be added $\pm 15\%$ tolerance.

Recommended Wave Soldering Profile



Part No.	LG-05IR4C94A-1034C	Page	4 of 9
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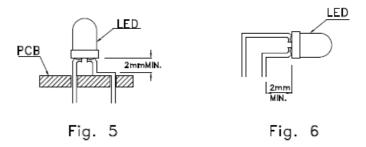
LIGHT ELECTRONICS CO., LTD. Part No. LG-05IR4C94A-1034C 6 of 9 Page



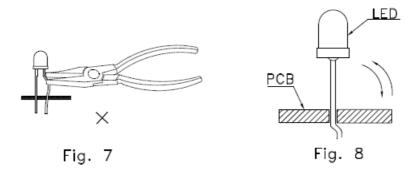


LEAD FORMING PROCEDURES

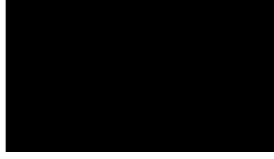
1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend (Fig.5 and Fig.6).

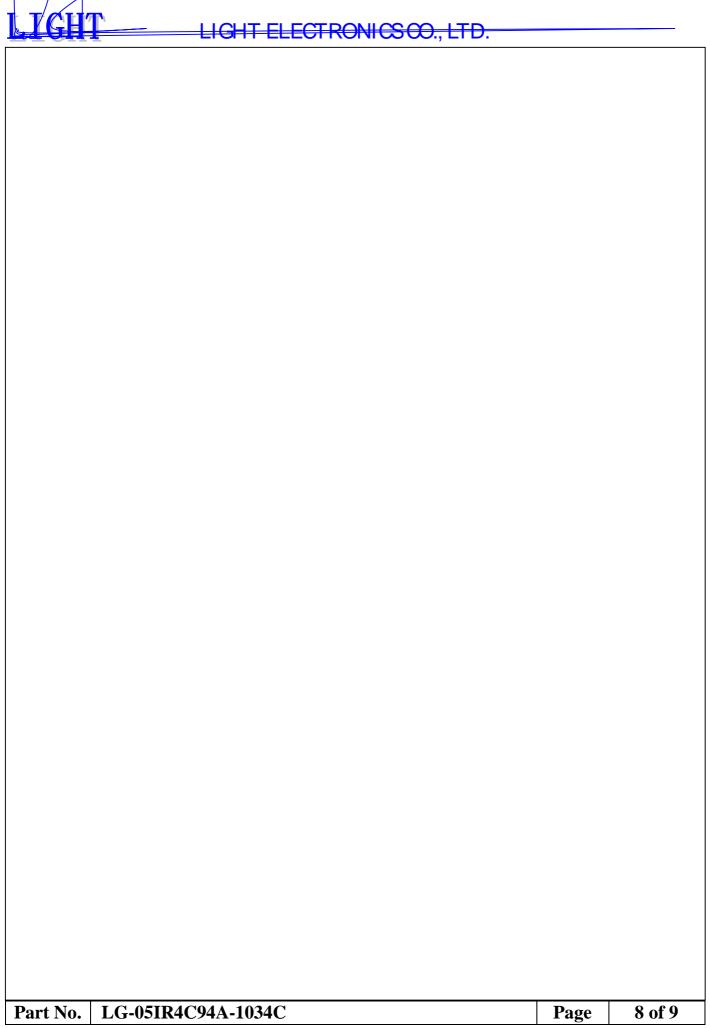


- 2. Lead forming or bending must be performed before soldering, never during or after soldering.
- 3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
- 4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB (Fig.7).
- 5. Do not bend the leads more than twice(Fig.8)



6. After soldering or other high-temperature assembly, allow the LED to cool down to 50 before applying force (Fig.9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with LIGHT representative for proper handling procedures.









Infrared Emitting Diode Specification

●Commodity: Infrared emitting diode

●Intensity Bin Limits (At 20mA)

BIN CODE	Min. (mW/sr)	Max. (mW/sr)
18	2.2	2.6
19	2.6	3.1
20	3.1	3.7
21	3.7	4.4

NOTE: The Ie guarantee should be added ± 15% tolerance.

Part No.	LG-05IR4C94A-1034C	Page	9 of 9
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